Record of Letter Ballot Review by TC Chapter for Procedural Review

Region/Locale: Japan

Global Technical Committee: Silicon Wafer

TC Chapter Cochairs: Tetsuya. Nakai/SUMCO, Naoyuki.Kawai /Meiji University

Standards Staff: Junko Collins

	Scheduled in Background Statement	Actual
Date	12/14/2017	12/14/2017
Location	Tokyo Big Sight, Tokyo Japan	Tokyo Big Sight, Tokyo Japan
Reason for Change of Date and/or Location (if changed)		

Note: See Regulations ¶ 9.5 Exception for allowable reason to change.

I. Document Number and Title

Document Number	Document Title
6267	REAPPROVAL OF SEMI MF1188-1107 (Reapproved
	0912)
	TEST METHOD FOR INTERSTITIAL OXYGEN
	CONTENT OF SILICON BY INFRARED ABSORPTION
	WITH SHORT BASELINE

II. Tally

Standards staff to fill in.

Voting Tally: As-cast tally after close of voting period

Note: A minimum of 60% of the Voting Interests that have TC Members within the global technical committee that issued the Letter Ballot must return Votes. (*Regulations* ¶ 9.7.1.1)

Voting Tally (with example values):

Returned Votes		Distribution		Return Rate	
57	÷	95	=	60.0%	≥60%
25]_				
0		Total	Vote	rs with Rejects	0
31]				
	57 25 0	57 ÷ 25	57 ÷ 95 25 0 Total	57 ÷ 95 = 25 0 Total Vote	57 ÷ 95 = 60.0% 25 0 Total Voters with Rejects

Note: See Regulations § 3.2.1 for definition of Voting Interest.

III. Rejects: No Rejects

IV. Other Technical Issues: None

Note: TC Chapter may choose to address a technical issue that is not part of a Negative received on a Letter Ballot (i.e., a Comment or a reason not addressed by a Vote response) by handling it as a Negative and finding it related and technically persuasive. The TC Chapter may then fail the Document or address such technical issue by using the procedure defined in *Regulations* § 9.6.4.3 to make a technical change to the Document. (*Regulations* ¶ 9.6.2.4.5)

V. Comments: No comments

VI. Editorial Changes Other than Those Voted on in § V None

Original section/paragraph number and at least one full sentence are required in "FROM" and "TO" fields.

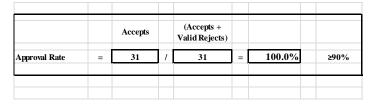
VII. Approval Conditions Check

VII. - (i). Approval Rate

APPROVAL CONDITION 1: All Negatives have been discussed and were withdrawn, found not related, found not persuasive, or addressed by a technical change. (*Regulations* ¶ 9.7.1.2)

APPROVAL CONDITION 2: At least 90% of the sum of valid Voting Interest Accept and Voting Interest Reject Votes must be Accept. (*Regulations* ¶ 9.7.1.3)

Note: If both approval conditions are not satisfied, the Document fails.



VII. – (ii) Approval Level (check one)

Note: See Regulations § 9.7.2 for further information.



Globally Approved (No Ratification Ballot needed):

The Letter Ballot meets the Letter Ballot approval conditions for the global technical committee.



Need a Ratification Ballot:

The Letter Ballot meets the Letter Ballot approval conditions for the TC Chapter and a Ratification Ballot will be issued to validate technical changes.

VIII. Safety Check

Note: See Regulations § 15 for further information.

	X	Th is s	This is not a Safety Document, when all safety-related information is removed, the Document is still technically sound and complete. (<i>Regulations</i> ¶ 8.7.1)						
Motion			This is a Safety Document , when all safety-related information is removed, the Document is not technically sound and complete. (<i>Regulations</i> ¶ 8.7.2)						
				safety Checklist (<i>Regulations</i> ¶ 15.3) is complete and has been included with the Document broughout the balloting process. (<i>Regulations</i> ¶ 15.1.2)					
ı	Vloti	Iotion by/2 nd by Ryuji Takeda (GlobalWafers Japan)/Tsuyoshi Otsuki (SEH)							
Discussion									
	Vote 11Y-0 N; Motion passed								

IX. Intellectual Property (IP) Check

Note: This Letter Ballot may cover all or part of a Standard or Safety Guideline. This IP check applies to the entire Standard or Safety Guideline. See *Regulations* § 16 for further information.

х	mate	The TC Chapter meeting chair asked those participating, if they were aware of any potentially material patented technology or copyrighted items* in the Standard or Guideline. (<i>Regulations</i> ¶ 8.8.1)							
	X	No potentially material patented technology or reproduction of copyrighted items is known.							
		copy copy	righted iter right releas	rerial patented technology or reproduction of ms is known, but a Letter of Assurance (LOA) or se letter for such items has been obtained or the TC Chapter.					
		use o	otentially material patented technology or reproduction of copyrighted items is known and e of such materials is technically justified by the TC Chapter, but an LOA or copyright ease letter for some of the item(s) has NOT been obtained or presented to the TC Chapter.						
	~		Ask ISC f	for special permission to publish.					
	Motion		Quit activ	ty.					
			Wait for L	OA for patented technology or release of copyrighted items.					
	Motion by/2 nd by		y/2 nd by						
	Discussion			XXXX					
	Vote			XX Y-XX N					
		Final Action			Motion passed				
	Final Action				Motion failed				

^{*} Note: Such potentially material patented technology or copyrighted items might have become known since the Standard or Safety Guideline was last reviewed, or might become relevant due to this Letter Ballot.

X. Action for This Document

		This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.				
ion		This Document passed TC Chapter review with editorial changes and will be forwarded to the ISC A&R SC for procedural review.				

This Document failed TC Chapter review and will be returned	to the TF for rework.			
This Document failed TC Chapter review and work will be disc	ontinued.			
Motion by/ 2 nd by Ryuji Takeda (GlobalWafers Japan)/Tsuyoshi Ots	Ryuji Takeda (GlobalWafers Japan)/Tsuyoshi Otsuki (SEH)			
Discussion	None			
Vote 11 Y-0 N	11 Y-0 N			
Final Action X Motion passed Motion failed				

Standards staff to record the result of the A&R procedural review here:

		Approved for publication					
A&R		Approved pending acceptance of the Ratification Ballot					
AON		Not approved					
	Re	Reason:					